

TECHNIQUES FOR PROVIDING EMI SHIELDING WITHIN
A CIRCUIT BOARD COMPONENT

ABSTRACT OF THE DISCLOSURE

5 A circuit board component includes a substrate having non-conductive material
and conductive material supported by the non-conductive material. The conductive
material defines a circuit board interface, a die interface, a heat spreader interface, and
(iv) a set of connections which interconnects the circuit board interface, the die interface,
and the heat spreader interface. The component further includes a die coupled to the die
10 interface. The die includes integrated circuitry which is configured to electrically
communicate with a circuit board when the circuit board couples to the circuit board
interface. The component further includes a heat spreader coupled to the heat spreader
interface. The heat spreader is configured to dissipate heat from the die. The heat
spreader in combination with the heat spreader interface forms an electromagnetic
15 interference shield when a portion of the circuit board interface connects to a ground
reference of the circuit board.